

**LOW-TEMPERATURE FLUX FOR SOLDERING
NICKEL-TITANIUM ALLOYS AND OTHER METALS**

ABSTRACT

- 5 **[0074]** A low-temperature flux is described which dissolves the refractory oxide layer from a shape memory alloy containing both nickel and titanium, such as Nitinol, and from other metals like stainless steel. The flux is particularly useful for preparing shape memory alloy members for soldering and permits joining of such members to other members, comprising, for example, stainless steel, used in structures like medical
- 10 devices. The flux is a non-aqueous molten salt formulated on eutectic mixtures of KOH (potassium hydroxide), NaOH (sodium hydroxide) and LiOH (lithium hydroxide), with melting temperatures in a range from about 170° C to about 226° C.